

**Amendments to the Specification:**

On page 1 of the application, please insert the following section prior to the section captioned "BACKGROUND":

**RELATED APPLICATIONS**

**The present application is a continuation of U.S. Application Serial No. 10/340,256 entitled MOUNTING FOR A PACKAGE CONTAINING A CHIP filed January 10, 2003, which is a continuation of U.S. Application Serial No. 09/813,485 entitled MOUNTING FOR A PACKAGE CONTAINING A CHIP filed March 20, 2001 and issued as U.S. Patent No. 6,545,345 on April 8, 2003.**

Please amend the paragraph beginning on page 5, line 15 and ending on page 5, line 19 as follows:

Body 24 has a first surface 24(a), an opposite planar second surface 24(b), and peripheral side surfaces 26e 24c. Typically, body 24 may be formed by molding or pouring and then curing a resin material (e.g., an epoxy resin). Where body 24 is molded, as in this example, side surfaces 26e 24c typically will be tapered to accommodate release from the mold.